



Product Specification :	ISSUED BY: Engineering Dept	
Subject : SCT0800 Series Specification	Date Issued	2015/06/02
	Date Revised	2016/06/27

INDEX

- 1.Scope
- 2.Specification and Part number
- 3.Disposal of Material and surface
- 4.Ratings and applicable wires
- 5.Performance
 - 5- 1. Electrical Performance.
 - 5-2. Mechanical Performance
 - 5-3. Environmental Performance and Others
6. Insertion/Withdrawal Force
7. SMT Infrared Reflow Condition



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1. Scope

This specification applies to SCT0800 connector series, contains the product performance, test methods and inspection requirements.

2. Spec and Part number

Specification	Production No.	Picture of Product
Terminal	/	/
Housing	SCT0800HI-xxBWT501	NONE
Wafer	SCT0800WVS-xxF1xx501 SCT0800WRS-xxF1xx501	NONE

3. Disposal of Material and surface

Specification	Materials	Disposal of Surface
Terminal	/	/
Housing	PA66	UL 94V-0
Wafer	Base	LCP
	PIN	Phosphor Bronze
	Solder tab	Brass
		Tin Plated:Over 70 p" .Nickel:Over 30 p" Gold Plated :Gold Flash" ~3p" .Nickel:Over 30 p"
		Tin Plated:Over 70 p" .Nickel:Over 30 p" Gold Plated :Gold Flash" ~3p" .Nickel:Over 30 p"

(Please Refer to the Project drawing for the above Specification)

4. Ratings and applicable wires

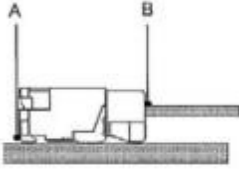
Item	Standard	
Rated Voltage (Max.)	30V	[AC/DC]
Rated Current (Max.)	0.5A	
Ambient temperature Range	- 25 C~ + 85 C	
Applicable wire insulation O. D	AWG 32#~26# Insulation O. D. 0.38mm(Max.)	

* Including terminal temperature rise.

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5. PERFORMANCE

5-1. Electrical Performance.

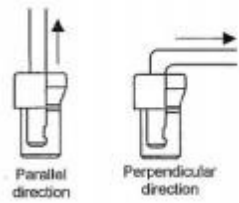
Item		Test Condition	Requirement
5-1-1	Contact Resistance	Mate connectors, measure by dry circuit, 20mV MAX, 10mA. (Based upon EIA-364-06A).	Initial : 20 milliohms Max. After Test : 40 milliohms Max.
			
5-1-2	Insulation Resistance	Mate connectors, apply 250V DC between adjacent terminal or ground. (Based upon EIA-364-21B/ MIL-STD-202 Method 302 Cond. B)	100 Megohms Min.
5-1-3	Dielectric Strength	Mate connectors, apply 250V AC for 1 minute between adjacent terminal or ground. (Based upon EIA-364-20A/MIL-STD-202 Method 301)	No Breakdown and Flashover
5-1-4	Contact resistance on crimped portion	Crimp the applicable wire on to the terminal measure by dry circuit 20mV MAX, 10mA.	20 milliohms Max.

5-1 Electrical Performance

Item		Test Condition	Requirement
5-2-1	Insertion & Retention Force	Insert and withdraw Connectors at the speed rate of 25.4±3mm/minute.	Refer to paragraph 6

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5-2. Mechanical Performance.

Item		Test Condition	Requirement	
5-2-2	Wire Retention Force	Apply axial pull out force at the rate of 25.4±3mm/minute terminal assembled in the housing. 	Parallel	perpendicular
			6N {0.6kgf} Min.AWG#32	2N {0.2kgf} Min.AWG#32
			4N {0.4kgf} Min.AWG#36	1.5N {1.5kgf} Min.AWG#36
5-2-3	Pin Retention Force	Apply axial push force at the speed of 25.4±3mm/minute.	2.5N {0.25kgf} Min.	

5-3. Environmental Performance and Others.

Item		Test Condition	Requirement	
5-3-1	Repeated Insertion/Withdrawal	When mated up to 30 cycles repeatedly by the rate of 10 cycles per minute.	Contact Resistance	40 milliohms Max.
5-3-2	Temperature Rise	Carrying rated current load. (UL 1977)	Temperature rise	30 CMax.
5-3-3	Vibration	Amplitude: 1.5 mm P-P Sweep time: 10~55~10 HZ in 1 minute Duration: 2 hours in each X.Y.Z axials . (Based upon EIA-364-28B/ MIL-STD-202 Method 213B Cond.A)	Appearance	No Damage
			Contact Resistance	40 milliohms Max.
			Discontinuity	1 micro-second Max.



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Item		Test Condition	Requirement	
5-3-4	Shock	490m/s ² {50G}, 3 strokes in each X.Y.Z. axes. (Based upon EIA-364-27B/MIL-STD-202 Method 213B Cond.A)	Appearance	No Damage
			Contact Resistance	40 milliohms Max.
			Discontinuity	1 micro-second Max.
5-3-5	Heat Resistance	85 ± 2C, 96 hours. (Based upon MIL-STD-202 Method 108A Cond. A)	Appearance	No Damage
			Contact Resistanc	40milliohms Max.
5-3-6	Cold Resistance	-25 ± 5C, 96 hours. (Based upon EIA-364-105)	Appearance	No Damage
			Contact Resistanc	40milliohms Max.
5-3-7	Humidity	Temperature: 40 ± 2 C Relative Humidity: 90 ~ 95 % Duration: 96 hours (Based upon EIA-364-31A/ MIL-STD-202 Method 103B Cond. B)	Appearance	No Damage
			Contact Resistance	40milliohms Max.
			Die lect ric St rength	Must meet 5-1-3
			Insulation Resistance	40Megohms Min.
5-3-8	Temperature Cycling	5 cycles of :a) -55C30 minutes. b) +85C30 minutes. (Based upon EIA-364-32B)	Appearance	No Damage
			Contact Resistance	40milliohms Max.
5-3-9	Salt Spray	24 ± 1 hours exposure to a salt spray f rom the 5 ± 1% solution at 35 ± 2C. (Based upon EIA-364-26A/MIL-STD-202 Method 101D Cond.B).	Appearance	No Damage
			Contact Resistance	40milliohms Max.
5-3-10	Solder-ability	Soldering Time: 5 ± 0.5second . Solder Temperature: 245 ± 5C. (Based upon EIA-364-52)	Solder Wetting	95% of immersed area must show no voids, pin holes.

Item		Test Condition	Requirement	
5-3-11	Solder-Resistance	Soldering time:5~10 sec solder. Temperature:260+5/-5C. (Based upon EIA-364-56A)	Appearance	No Damage

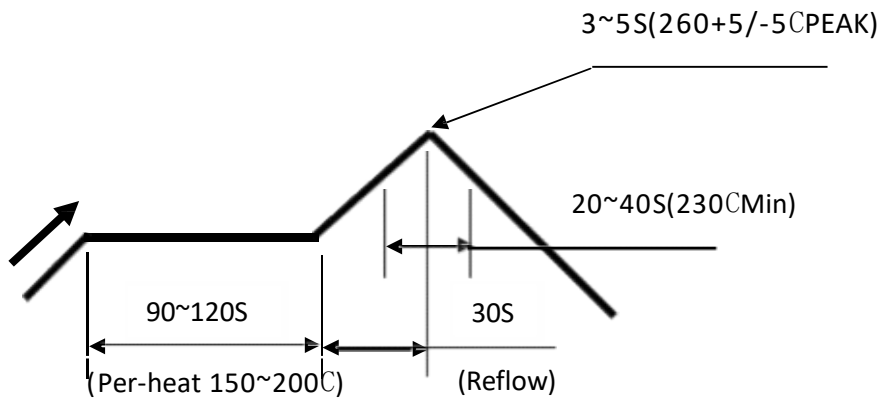
6. INSERTION/ WITHDRAWAL FORCE < Connector matingforce>

Note: Insertion and Withdrawal for 30 Cycles

No. of CKT	First Insertion (kgf Max.)	30 th Withdrawal (kgf Min.)	No. of CKT	First Insertion (kgf Max.)	30 th Withdrawal (kgf Min.)
02	1.20	0.08	13	2.30	0.52
03	1.30	0.12	14	2.40	0.56
04	1.40	0.16	15	2.50	0.60
05	1.50	0.20	16	2.60	0.64
06	1.60	0.24	17	2.70	0.68
07	1.70	0.28	18	2.80	0.72
08	1.80	0.32	19	2.90	0.76
09	1.90	0.36	20	3.00	0.80
10	2.00	0.40	21	3.10	0.84
11	2.10	0.44	22	3.20	0.88
12	2.20	0.48			

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7. SMT SMT INFRARED REFLOW CONDITION



TEMPERATURE CONDITION GRAPH/ (TEMPERATURE ON BOARD PATTERNSIDE)

Notes: Please check the reflow soldering condition by your own devices beforehand. Because the condition changes by the soldering devices, P.C. boards, and so on.